

ACUROS® CQD® 640L GigE eSWIR Camera

ACUROS-0640-GigE-004

The ACUROS CQD L-Series SWIR cameras feature large sensor area, low angular dependence and a short working distance for highly divergent emitters. ACUROS cameras deliver high resolution, high dynamic range and very high detectivity imaging to 2000 nm.

The L-Series cameras are designed for use exclusively in laser beam diagnostics, laser beam imaging and laser alignment applications.

SPECIFICATIONS

Table 1. ELECTRO-OPTICAL SPECIFICATIONS

Parameter	Value/Description
Sensor	ACUROS CQD sensor
Temperature Stabilization	Single-stage thermo-electric cooler
Sensor Array Format	640 x 512
Resolution	0.33 MP (megapixel)
Spectral Band	350–2000 nm
Array Size	9.6 mm x 7.7 mm, 12.3 mm diagonal
Pixel Pitch	15 µm x 15 µm
Max Frame Rate at Full Resolution	270 fps (8 bit), 180 fps (10, 12, 14 bit)
Pixel Operability	99.9% typical, 99.75% min
Bit Depth	8, 10, 12, 14 bit selectable
Integration Type	Snapshot global shutter
Trigger	External TTL
Integration Time	100 µs to 4 s
Dynamic Range	65 dB typical
Windowing & Windowing Frame Rate	Array centered. Scales inversely to window size
Laser Beam Fringeless Operation	Yes
Binning Arrays	2 x 2, 4 x 4
Non-uniformity Correction	2-point non-uniformity correction
Temporal Dark Noise	80/70/65 e ⁻ typical
Quantum Efficiency	See typical QE curve (Figure 4)



ORDERING INFORMATION

Part Number
ACUROS-0640-GigE-004

Features

- Large Sensor Size
- Short Working Distance for Highly Divergent Beams
- Low Angular Dependence
- Dynamic Range up to 70 dB
- Linear Photoresponse
- VGA Resolution
- TEC Cooling
- Low Noise
- GigE Vision
- Visible-eSWIR

Applications

- Laser Beam Diagnostics
- Laser Beam Imaging
- Laser Alignment

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Table 2. ENVIRONMENTAL & POWER SPECIFICATIONS, TYPICAL PERFORMANCE

Parameter	Value/Description
Operating Case Temperature	-20 °C to +55 °C
Power Consumption	6.5–12 W depending on TEC settings
Power Supply Voltage	6–16 V dc. POE not supported
Regulatory Compliance	CE mark

Table 3. MECHANICAL SPECIFICATIONS

Parameter	Value/Description
Dimensions Excluding Lens	6.1 x 6.1 x 9.8 cm
Weight Excluding Lens	505 grams
Lens Mounts	Standard mount. Inquire for other options.
Power Connector	Hirose 12-pin, HR10A-10R-12PB (71)
Trigger Connector	BNC

Table 4. SOFTWARE AND USER INTERFACE

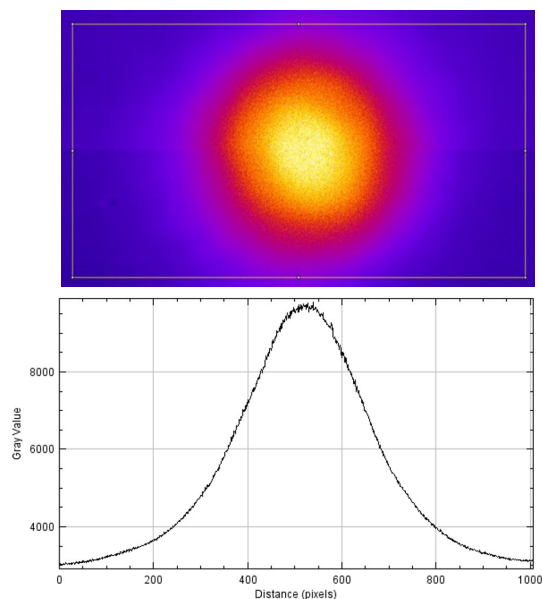
Parameter	Value/Description
Software Development Kit	Windows GUI
GenICam Compliance	Yes
Interface	GigE Vision



Figure 1.



Figure 2. GigE Vision Interface



1550 nm Laser image and corresponding line file
(false color added post image)

Figure 3. ACUROS CQD SWIR Camera Image of Laser

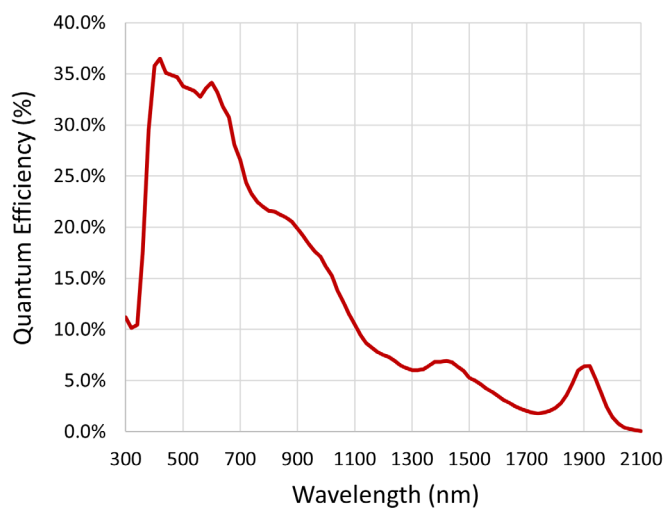


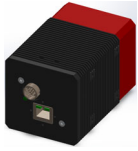
Figure 4. Typical QE Performance

REVISION HISTORY

Revision	Description of Changes	Date
3	Removed "eBUS SDK" from Software Development Kit due to change in licensing.	3/12/2026

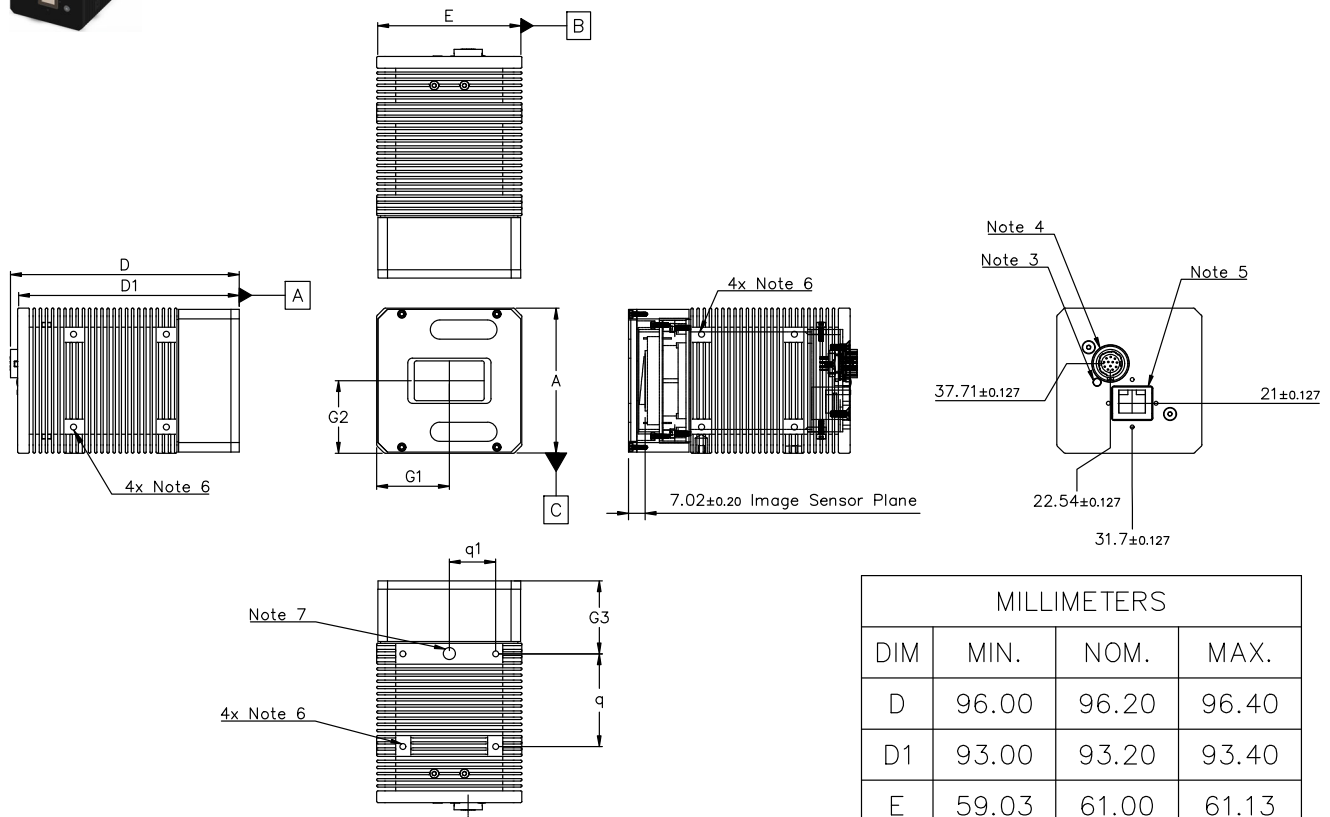
This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.





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CASE 810AD
ISSUE B

DATE 27 MAY 2025



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 2018.
2. CONTROLLING DIMENSION: MILLIMETER
3. POWER INIDCATOR
4. HIROSE 12 PIN CONNECTOR
5. GigE CONNECTOR
6. M3X0.5 DEPTH ∇ 3.0
7. 1/4-20 UNC DEPTH ∇ 5.08

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